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Title: Unit Disas	sembly for	WEEE	
Document Number / Disk File:	By:	Current Rev:	Date:
597-316-0100-00	Thinh Ta	0A	2/10/2016
Assemblies Covered: STORAGE, PROMISE JX30	), 3U RM 6G SA	S JBOD ( <b>316-0</b> 1	00-00)



Revision	Date	Revised By	Description of Changes
0A	9/08/2011	Thinh Ta	Initial Release

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### **Tools Required:**

#2 Phillips Screw Driver.
12-Inch Long #2 Phillips Screw Driver.

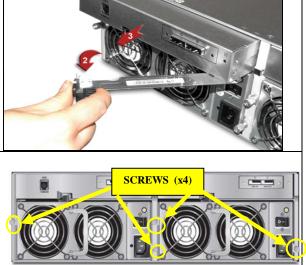
1.	Make sure the unit is powered off and remove the AC power cords if they are still plugged in by pulling them out. Remove SAS cables by squeeze the blue tab toward SAS connector to unlock then pulling them out. Remove serial cables by unlock the RJ- 11 tab and pulling them out.	Serial cables   SAS Cables     Power Connectors
	Discard the power cords, SAS cables, and Serial cables into the appropriate recycle bin.	
2.	<ul> <li>Removal of the thin films (if present) does not require any tools</li> <li>a. Remove the thin films (top, bottom, left and right sides) that wrapped around the enclosure</li> <li>Discard the thin films in the appropriate recycle bin.</li> </ul>	

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3.	<ul> <li>Removal of the Disk Drive Carriers does not require any tools <ul> <li>a. Remove the disk drive carriers by pressing the square button on each carrier assembly.</li> </ul> </li> <li>b. Pull the handle to the left and pull the carrier out of the drive bay, and put it aside.</li> <li>c. Repeat steps a and b for all 16 disk drive carrier.</li> </ul>	
4.	<ul> <li>Removal of the Drive from disk drive carriers requires a #2 Phillips screw driver.</li> <li>a. Remove all 4 screws (2 on each side) on the drive carrier and separate the drive from the carrier.</li> <li>b. Repeat step above for all 16 disk drives</li> <li>c. Discard the Drives, drive carriers and screws into the appropriate recycle bin.</li> </ul>	SCREWS (x4)

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5.	Removal of the IO Modu require any tools	les does not		

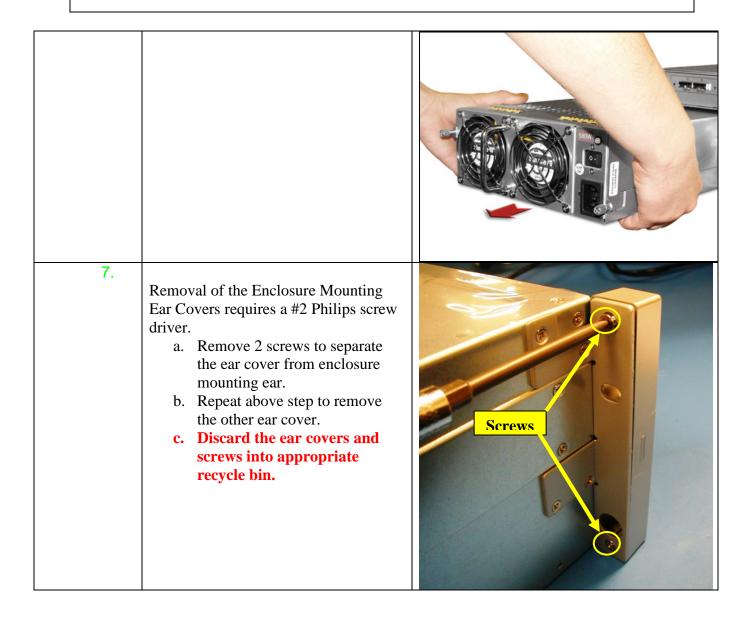
6	<ul> <li>hold on to the handle, pressing the locking tab to the right side to unlock it.</li> <li>b. Gently pull the handle <sup>3</sup>/<sub>4</sub> of the way out.</li> <li>c. Using two hands to grab and pull the IO Module away from the enclosure.</li> <li>d. Repeat steps <b>a,b</b>, and <b>c</b> for the other IO Module.</li> <li>e. <b>Discard the IO Module(s) into the appropriate recycle bin.</b></li> </ul>	
6.	<ul> <li>Removal of the Power Supplies requires a #2 Phillips screw driver. <ul> <li>a. Undo all 4 thumb screws (2 on each power supply) to separate both power supply) to separate both power supplies from the enclosure.</li> <li>b. Grap the handle and gently pull towards your body <sup>3</sup>/<sub>4</sub> way out.</li> <li>c. Use two hands grab and pull the power supply the remainder of the way out.</li> <li>d. Repeat step b and c for the other power supply.</li> <li>e. Discard the Power Supplies into appropriate recycle bin.</li> </ul> </li> </ul>	





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8.	<ul> <li>Removal of the Enclosure Mounting Ears requires a #2 Philips screw driver.</li> <li>a. Remove all 4 screws to separate the ear bracket from the enclosure.</li> <li>b. Repeat above step for the other side of ear bracket.</li> <li>c. Discard the ear brackets and screws into appropriate recycle bin.</li> </ul>	
9.	<ul> <li>Loosening top and bottom halves of the enclosure requires #2 Philips screw driver.</li> <li>a. Remove all 17 screws on the top half of the enclosure.</li> <li>b. Remove all 17 screws of bottom half.</li> <li>c. Remove all 9 screws on the enclosure right side</li> <li>d. Remove all 9 screws on the enclosure left side.</li> <li>e. Discard all screws into appropriate recycle bin.</li> </ul>	SCREWS (x17)

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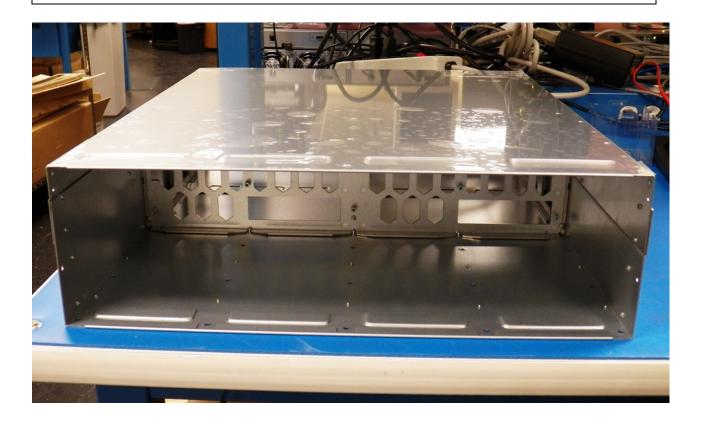
#### STORAGE, PROMISE JX30, 3U RM 6G SAS JBOD (316-0100-00)

	SCREWS (x 9)	SCREWS (x 9)
10.	<ul> <li>Removal of Drive Bay does not require any tools <ul> <li>a. Lift the enclosure top-half up away from bottom-half to disengage the pins and the drive side brackets.</li> <li>b. Grab the top bar and gently pull towards your body.</li> <li>c. Remove the top bar and three drive side brackets, which still attached to the top bar, completely out of enclosure.</li> </ul> </li> </ul>	PINS (x 20) TOP BAR
11.	<ul> <li>Disengage the top bar and drive brackets requires a #2 Philips screw driver.</li> <li>a. Remove all 3 screws holding the drive side brackets to the top bar.</li> <li>b. Discard the top bar, drive side brackets and all screws into appropriate recycle bin.</li> </ul>	CREWS (x3)

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12.	<ul> <li>Removal of the Drive Bay Brackets does not require</li> <li>a. Lift the enclosure to away from bottom- disengage the pins brackets.</li> <li>b. Grab the side brack slide it out of the e</li> <li>c. Repeat step a and b bracket.</li> <li>d. Discard both side appropriate recyce</li> </ul>	any tools cop-half up half to and the side ket and gently nclosure. b for other brackets into	SIDE	BRACKETS (x2)
13.	<ul> <li>Removal of the enclosurer requires a 12-inch long #2 screw driver.</li> <li>a. Remove all 14 screed disengage the driver and the enclosure.</li> <li>b. Grab the backplane pull out of the enclocher c. Disconnect the ribled.</li> <li>Discard the backplane screws, ribbon cale enclosure into apprecycle bin.</li> </ul>	2 Philips ews to e back plane e and gently osure. bon cable blane, ble, and the		(x14)

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## STORAGE, PROMISE JX30, 3U RM 6G SAS JBOD (**316-0100-00**)



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Recycling/Material Code	Important Information		
Material /Components, which must be removed and treated separately			
Printed circuit boards	Enclosure Back plane, Power Supply, IO		
	Modules		
Disk Drives	All HDD's		
Material /Components, which can disturb certain recycling processes			
Copper			
Lead			
Material /Components, through which benefits can normally be achieved			
Cold Rolled Steel	Enclosure, Enclosure Mounting Ears, and Rack		
	Mount Rails.		
* ABS	Power Supply and IO Module Barriers, Ear		
	Covers		
Cables	Power Cords, SAS Cables, Serial Cables		
Fans			
Aluminum	Drive Bay Brackets		
Special notes			
* Flame retardant of plastics do not contain PBI	3 and PBDE.		

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0A

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#### Annex A

Producer:	<company addressing="" name,="" on="" other="" producer="" the=""></company>
	< Product category as in Annex IA of WEEE Directive, or type of equipment as in Annex 1B of WEEE Directive, or producer's Product Family, or single products identified by brand and model name >

Component or Material	Remarks / Location
Battery (internal *) containing Mercury (Hg)/ NiCad/Lithium/ Other	NONE
Backlighting lamps of LCD/TFT or similar screens containing Mercury (Hg)	NONE
Mercury (Hg) in other applications**	NONE
Cadmium**	NONE
Gas discharge lamps	NONE
Plastic containing ruminated flame retardants other than in Printed Circuit Assemblies ***	NONE
Liquid Crystal Displays with a surface greater than 100 cm2	NONE
Capacitors with PCB's	Power Supplies, IO Modules, J Backplane
Capacitors with substances of concern**** + height > 25 mm, diameter > 25 mm or proportionately similar volume	NONE
Asbestos	NONE
Refractory ceramic fibres	NONE
Radio-active substances	NONE
Beryllium Oxide	NONE
Other forms of Beryllium	NONE
Gasses - which fall under Regulation (EC) 2037/2000 and all hydrocarbons (HC).	NONE
Components with pressurised gas which need special attention (Pressure > 1,5 bar) *****	NONE
Liquids ***** if volume > 10 cl (or equivalence in weight, e.g. for PCB, oil)	NONE
Mechanical components that store mechanical energy (i.e. springs) or equivalent parts which need special attention ***** (diameter > 10 mm and height > 25 mm or proportionally similar volume and expanding)	NONE
PBDE (deca- & octa-BDE) in Directive 2006/122/EC	NONE

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Arrow indicates the need for the location of the compartment/ substances within the product. When the location of a substance/ components is requested, it is at part level, e.g. main board, housing etc

\* Internal means that batteries can only be removed by opening the product by means of (a) tool(s).

\*\* Substances are considered to be in the product if present above the levels specified in Commission Decision 2005/618/EC related to Directive 2002/95 (EC) (RoHS Directive) or if their use is permitted through exemptions in the Annex of Directive 2002/95(EC)

\*\*\* To be coherent with industry current standards and practices on tracking of plastic parts, Directive 2002/96 (EC) Annex II requirement is understood to focus on plastic parts that weight more than 25 g.

\*\*\*\* Substance of concern other than PCB, to be specified/ addressed further in the context of Directive 2002/96 (EC) Annex II national requirements and European developments

\*\*\*\* Needs of equivalent nature as those for maintenance, service manuals and installation for safety purposes.